

Title (en)

Polishing composition and polishing method

Title (de)

Polierzusammensetzung und Polierverfahren

Title (fr)

Composition de polissage et procédé pour polir

Publication

**EP 1760099 B1 20121226 (EN)**

Application

**EP 06119861 A 20060831**

Priority

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- JP 2005252640 A 20050831

Abstract (en)

[origin: EP1760099A2] A polishing composition contains a compound represented by the general formula (1) below and abrasive grains. In the general formula (1), X represents a residue of polyether polyol (having a polyether chain containing an oxyethylene group in an amount of 20 to 90% by mass) derived from a compound having an active hydrogen atom and an alkylene oxide; m represents an integer of 2 to 8, which is equal to the number of hydroxy groups contained in a single polyether polyol molecule; Y and Z represent a lower alcohol residue to which ethylene oxide or propylene oxide is added by addition polymerization, an alkyl group or an alkylene group, respectively; and n is an integer of 3 or more.

IPC 8 full level

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CPC (source: EP KR US)

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